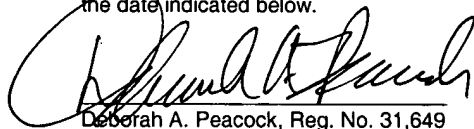


PATENT

IFW

I hereby certify that this paper is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, Virginia 22313-1450, on the date indicated below.


Deborah A. Peacock, Reg. No. 31,649

6/17/04
Date

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No. : 10/799,905
Applicant(s) : Thomas J. O'Keefe, et al.
Filed : March 12, 2004
Title : PROCESS FOR SPONTANEOUS DEPOSITION FROM AN ORGANIC SOLUTION

TC/A.U. : 1762
Examiner : Unknown

Docket No. : 31550-1001

Commissioner for Patents
PO Box 1450
Alexandria, Virginia 22313-1450

INFORMATION DISCLOSURE STATEMENT

SIR:

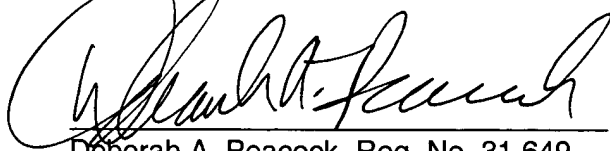
Pursuant to 37 C.F.R. §§ 1.97 and 1.98 and to the duty of disclosure set forth in 37 C.F.R. § 1.56, the Examiner in charge of the above-identified application is requested to consider and make of record the references listed on the PTO 1449 submitted herewith.

Although the information submitted herewith may be "material" to the Examiner's consideration of the subject application, this submission is not intended to constitute an admission that such information is "prior references" as to the claimed invention.

In accordance with 37 C.F.R. § 1.97(g), the filing of this Information Disclosure Statement shall not be construed to mean that a search has been made.

The Information Disclosure Statement submitted herewith is being filed before the mailing date of a first Office Action on the merits, Therefore, no fee or certification is required. 37 C.F.R. § 1.97(b).

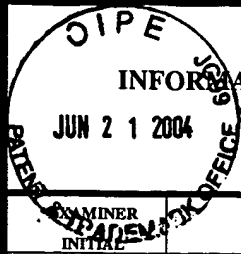
Respectfully submitted,

A handwritten signature in cursive script, appearing to read 'Deborah A. Peacock', written over a horizontal line.

Deborah A. Peacock, Reg. No. 31,649
Direct line: (505) 998-1501

Enclosures: PTO Form 1449
Eighteen (18) References

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INFORMATION DISCLOSURE CITATION

(Use several sheets if necessary)

Docket Number (Optional)

31550-1001

Application Number

10/799,905

Applicant(s)

Thomas J. O'Keefe, et al.

Filing Date

March 12, 2004

Group Art Unit

1762

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

"Spontaneous, Non-Aqueous Electrochemical Deposition of Copper and Palladium on Al and Al(Cu) Thin Films," R. Fang, H. Gu, J. O'Keefe and T.J. O'Keefe, University of Missouri-Rolla, Dept. of Metallurgical Engineering and Materials Research Center; W-S. Shih, Brewer Science, Inc.; K.D. Leedy and R. Cortez, Air Force Research Laboratory, Sensors Directorate

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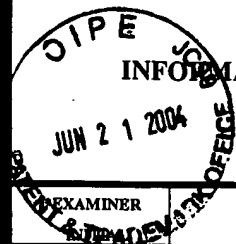
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EXAMINER

DATE CONSIDERED

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